

BEST AVAILABLE COPY**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously presented) A tamper-evident and/or tamper-resistant electronic module comprising an electronic component, a tamper-evident and/or tamper-resistant sheet, and encapsulant material, said component being encapsulated in said encapsulant material, said sheet overlying said component, said sheet comprising a multi-layer sheet, said tamper-evident and/or tamper-resistant sheet being encapsulated in said encapsulant material, and said encapsulant material being opaque so that said tamper-evident and/or tamper-resistant sheet cannot be seen, a plurality of said layers of said sheet being selected from the groups:

- (i) an electromagnetic radiation shield layer;
- (ii) a tell-tale electrically conductive trip wire defining a convoluted meandering pathway on said layer, said trip wire meandering in a pattern which substantially covers said electronic component in a space filled area of said layer;
- (iii) a layer having the features of (ii), and in which the pathway comprises a fractal pattern;
- (iv) a layer having the features of (ii), and in which a second tell-tale trip wire extends alongside a first tell-tale trip wire so that they meander as a spaced pair.
- (v) an active electromagnetic masking emission layer adapted to emit electromagnetic radiation.

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2. (Original) A module according to claim 1 wherein said layers are of a flexible electrically insulating plastics material and said shield and/or pathways are electrically conductive coatings or regions carried by said flexible plastics material.

3. (Original) A module according to claim 2 wherein said shield and/or pathways are printed onto said layers.

4-5. (Cancelled)

6. (Original) A module according to claim 1 wherein said tamper-evident and/or tamper-resistant sheet has one or more layers selected from group (ii) to (iv) sandwiched between two layers from the group (i).

7. (Original) A module according to claim 6 wherein said sheet has at least two layers in accordance with any of groups (ii) to (iv), with the meandering pathway of one layer being displaced when viewed in plan from the pathways of the other layer so that as seen in plan projection the pathways of said one and said other layers overlies, at least in part, different parts of the plan area of said component, and wherein said one layer and said other layer are sandwiched between two layers from group (i).

8. (Original) A module according to claim 1 wherein said sheet has an undulating, contoured, shape so that a said layer is not disposed in a precisely flat plane.

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9. (Previously presented) A module according to claim 8 wherein said sheet is encapsulated in said encapsulant which defines a body having a surface, and wherein at different regions of said body surface said layer is at different depths within said body from said surface.

10. (Original) A module according to claim 9 wherein said component has projecting hill portions and valley portions between said projecting hill portions, and wherein said sheet undulates with hills and valleys complementary to said hill and valley portions of said component.

11. (Previously presented) A module according to claim 1 wherein a first of said tamper-evident and/or tamper-resistant sheets extends above said component, and a second of said tamper-evident and/or tamper resistant sheets extends below said component.

12. (Original) A module according to claim 11 wherein said first and second sheets are separate sheets.

13. (Original) A module according to claim 12 wherein said first and second sheets are made separately and do not have identical layer structures.

14. (Previously presented) A module according to claim 11 wherein said first and second sheets have main body portions having a generally flat shape and wherein side portions of the tamper-evident and/or tamper-resistant sheets extend between said main body portions of

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said first and second sheet transversely to the main body portions, so as to extend over side regions of said electronic component.

15. (Previously presented) A module according to claim 14 wherein said component is substantially completely enclosed in a container of said tamper-evident and/or tamper-resistant sheet.

16. (Original) A module according to claim 1 wherein a power supply is encapsulated within said encapsulant and at least one sensor is provided to monitor at least one layer in order to determine whether an expected condition or signal is observed by said sensor.

17. (Original) A module according to claim 16 wherein said component comprises a printed circuit board.

18. (Original) A module according to claim 17 wherein said printed circuit board has a clock and is adapted to timestamp data, and has a control processor, and wherein said processor is adapted to generate a tamper-signal upon detection of a tampering signal from one of said layers.

19. (Original) A module according to claim 18 wherein said control processor is adapted to perform one or more of the actions:

- (i) stop providing timestamp signals;
- (ii) issue a tamper alarm;

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(iii) record in a memory the occurrence of a tamper event;
upon the generation of said tamper-signal.

20. (Previously presented) A module according to claim 1 wherein a thin sheet of frangible material is embedded in said encapsulant overlaying said component, said sheet of frangible material being of such thickness that it cracks or breaks if an attempt is made to drill or cut through it with a laser drill.

21. (Original) A module according to claim 20 wherein said sheet of frangible material has at least one of: (i) a diffusive layer adapted in use to diffuse a laser beam so as to reduce the energy intensity of the light which passes through said frangible sheet; (ii) a reflective layer adapted in use to reflect at least a substantial part of the light of an incident laser beam.

22. (Previously presented) A module according to claim 1, the module having a PCI card configuration.

23-47. (Cancelled)

48. (Original) A module according to claim 1 wherein said component comprises one of:

- (i) a timestamping clock adapted to timestamp data; or
- (ii) a PCB having a timestamping clock adapted to timestamp data.

49-51. (Cancelled)